# MMBT2131T1

# General Purpose Transistors

# **PNP Bipolar Junction Transistor**

### (Complementary NPN Device: MMBT2132T1/T3)

NOTE: Voltage and Current are negative for the PNP Transistor.

#### Features

• Pb–Free Package is Available

#### **MAXIMUM RATINGS** ( $T_C = 25^{\circ}C$ unless otherwise noted)

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V <sub>CEO</sub>	30	V
Collector-Base Voltage	V <sub>CBO</sub>	40	V
Emitter-Base Voltage	V <sub>EBO</sub>	5.0	V
Collector Current	۱ <sub>C</sub>	700	mA
Base Current	Ι <sub>Β</sub>	350	mA
Total Power Dissipation @ $T_C = 25^{\circ}C$ Total Power Dissipation @ $T_C = 85^{\circ}C$ Thermal Resistance, Junction–to–Ambient (Note 1)	Ρ <sub>D</sub> Ρ <sub>D</sub> R <sub>θJA</sub>	342 178 366	mW mW °C/W
Total Power Dissipation @ $T_C = 25^{\circ}C$ Total Power Dissipation @ $T_C = 85^{\circ}C$ Thermal Resistance, Junction–to–Ambient (Note 2)	P <sub>D</sub> P <sub>D</sub> R <sub>θJA</sub>	665 346 188	mW mW °C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

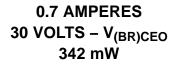
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

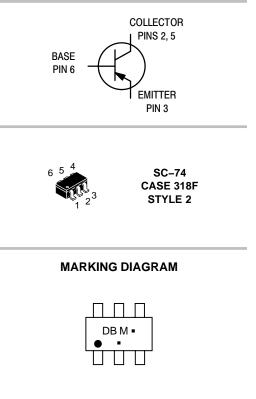
- 1. Minimum FR-4 or G-10 PCB, Operating to Steady State.
- Mounted onto a 2" square FR-4 Board (1" sq. 2 oz Cu 0.06" thick single sided), Operating to Steady State.



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DB = Device Code

- M = Date Code\*
- = Pb-Free Package

(Note: Microdot may be in either location) \*Date Code orientation may vary depending

upon manufacturing location.

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MMBT2131T1	SC-74	3000/Tape & Reel
MMBT2131T1G	SC-74 (Pb-Free)	3000/Tape & Reel

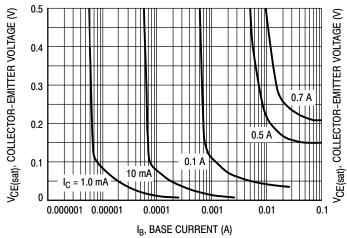
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

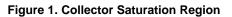
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## MMBT2131T1

## **ELECTRICAL CHARACTERISTICS** ( $T_C = 25^{\circ}C$ unless otherwise noted)

Characteris	Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	(I <sub>C</sub> = 100 μA)	V <sub>(BR)CBO</sub>	40	-	-	V
Collector-Emitter Breakdown Voltage	V <sub>(BR)CEO</sub>	30	-	-	V	
Emitter-Base Breakdown Voltage	(I <sub>E</sub> = 100 μA)	V <sub>(BR)EBO</sub>	5.0	-	-	V
Collector Cutoff Current (Vo	I <sub>CBO</sub>	-		1.0 10	μΑ	
Emitter Cutoff Current	$(V_{EB} = 5.0 \text{ V}, I_C = 0 \text{ A})$	I <sub>EBO</sub>	_	-	10	μΑ
ON CHARACTERISTICS						-
DC Current Gain	$(V_{CE} = 3.0 \text{ V}, I_{C} = 100 \text{ mA})$	h <sub>FE</sub>	150	-	-	V
Collector-Emitter Saturation Voltage	$(I_{C} = 500 \text{ mA}, I_{B} = 50 \text{ mA})$	V <sub>CE(sat)</sub>	-	-	0.25	V
Collector-Emitter Saturation Voltage	(I <sub>C</sub> = 700 mA, I <sub>B</sub> = 70 mA)	V <sub>CE(sat)</sub>	-	-	0.4	V
Base–Emitter Saturation Voltage	(I <sub>C</sub> = 700 mA, I <sub>B</sub> = 70 mA)	V <sub>BE(sat)</sub>	-	-	1.1	V
Collector–Emitter Saturation Voltage $(I_C = 700 \text{ mA}, V_{CE} = 1.0 \text{ V})$		V <sub>BE(on)</sub>	-	-	1.0	V





150°C

25°C

-40°C

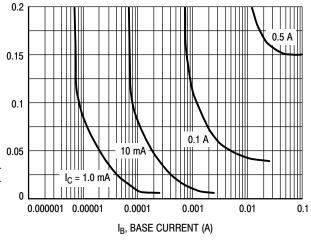


Figure 2. Collector Saturation Region

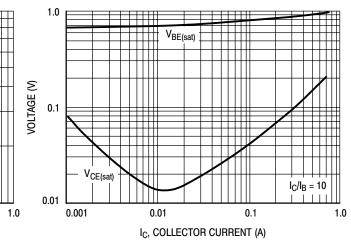


Figure 3. DC Current Gain

0.1

I<sub>C</sub>, COLLECTOR CURRENT (A)



## http://onsemi.com

V<sub>CE</sub> = 3.0 V

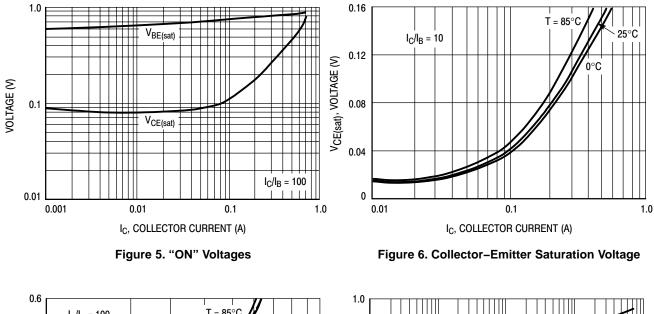
1000

100

0.01

h<sub>FE</sub>, DC CURRENT GAIN

## MMBT2131T1



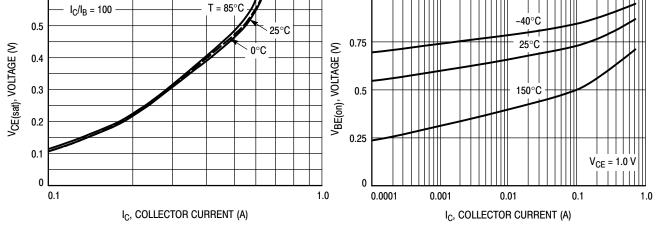


Figure 7. Collector–Emitter Saturation Voltage

Figure 8. V<sub>BE(on)</sub> Voltage

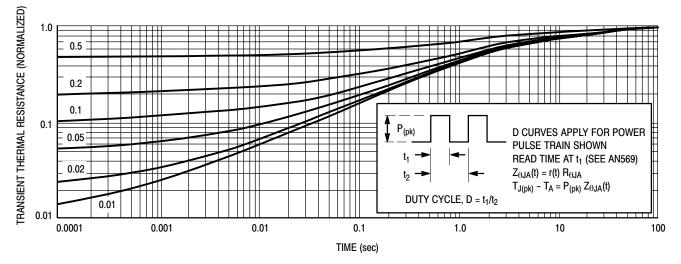
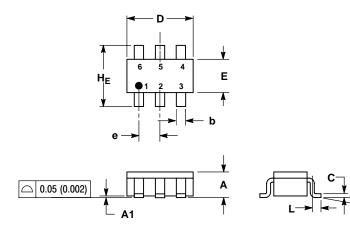


Figure 9. Thermal Response Curve

#### PACKAGE DIMENSIONS

SC-74 CASE 318F-05 **ISSUE L** 



## NOTES:

- 1. DIMENSIONING AND TOLERANCING PER
- ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD 3. THICKNESS IS THE MINIMUM THICKNESS
- OF BASE MATERIAL. 318F-01, -02, -03 OBSOLETE. NEW STANDARD 318F-04.

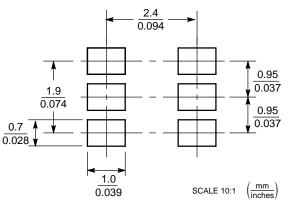
	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.90	1.00	1.10	0.035	0.039	0.043	
A1	0.01	0.06	0.10	0.001	0.002	0.004	
b	0.25	0.37	0.50	0.010	0.015	0.020	
с	0.10	0.18	0.26	0.004	0.007	0.010	
D	2.90	3.00	3.10	0.114	0.118	0.122	
Е	1.30	1.50	1.70	0.051	0.059	0.067	
е	0.85	0.95	1.05	0.034	0.037	0.041	
L	0.20	0.40	0.60	0.008	0.016	0.024	
HE	2.50	2.75	3.00	0.099	0.108	0.118	
θ	0°	-	10°	0°	-	10°	

- STYLE 2: PIN 1. NO CONNECTION
  - 2. COLLECTOR 3. EMITTER

4. NO CONNECTION

5. COLLECTOR 6 BASE

#### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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